C	Aterial Composit Copyright 2005. IPC, International and Pan-Am	Bannockb	urn, Illinois. A	ll rights reserved u ntions.	Inder both lev	nis docume vel parts, ti	ent is a declara he declaration	tion of the encompas	substances ses all low	s within the manufact er level materials for	urer listed which the	item. Note: i manufacture	f the item is an as r has engineering	sembly with lower responsibility.	
				Form Type * Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi				rials and M	als and Mfg Information					
Supplier Information	on														
Company name*			Company unique ID			1	Unique ID Authority				Respo	Response Date*			
onsemi											2023-0	2023-06-08			
Contact Name			Title - Contact]	Phone - Contact*				Email	Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative			Phone - Representative*				Email	Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Produ	Product-Env-Stewards@onsemi.com			
Requester Ite	Requester Item Number Mfr Iten		n Number Mfr Item Name				Effective Dat	fective Date Version Manufacturing Site			Weight*	UOM	Unit Type		
		NCP8110	NCP81109EMNTXG Single-Phase Voltag		tage Regulator with	h SVID	2023-06-08 PH1			118.03	mg	Each			
Manufacturing Pro	occess Information	l													
Terminal Plating / Grid Array Material To			erminal Base Alloy J-STD-020 MSL		J-STD-020 MSL R	ating	Peak Process Body Temperatu		re Max Time at Pea	k Tempera	ature Numb	per of Reflow Cyc	eles		
Matte Tin (Sn) - annealed CU			U Alloy 3			260 C 30		30	seconds 3						
Comments															
ATTENTION: MSL 3 R	Rated item requires Ba	ke and D	ry Pack (after	electrical test)											
For more information re	egarding material com	position 1	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU	(Pb), Mercury (Hg), Hexavalent Chro	RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).										
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of							
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).									
Exemption List Version	EL-2011/534/EU											
Declaration Signature												
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature	astislav Drska	Le										

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	3.48	mg	Supplier	Silicon (Si)	7440-21-3		3.48	mg
Die Attach Solder	3.37	mg	Supplier	Silver (Ag)	7440-22-4		0.0842	mg
			А	Lead (Pb)	7439-92-1	7a	3.1172	mg
			Supplier	Tin (Sn)	7440-31-5		0.1685	mg
Lead Frame	57.28	mg	Supplier	Silver (Ag)	7440-22-4		0.2291	mg
			Supplier	Tin (Sn)	7440-31-5		0.1432	mg
			Supplier	Zinc (Zn)	7440-66-6		0.126	mg
			Supplier	Chromium (Cr)	7440-47-3		0.1432	mg
			Supplier	Copper (Cu)	7440-50-8		56.6385	mg
Mold Compound-Black	49.82	mg		Epoxy Phenol Resin	proprietary data		5.2311	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		44.5889	mg
Plating	2.76	mg	Supplier	Tin (Sn)	7440-31-5		2.76	mg
Wire Bond - Au	1.32	mg	Supplier	Gold (Au)	7440-57-5		1.32	mg